

MOSFET Silicon N-Channel MOS

1. Applications

PFC stages, hard switching PWM stages and resonant switching PWM
PC, Silverbox, Adaptor, LCD & PDP TV, Lighting, Server power, Telecom power and UPS application.



2. Features

Low drain-source on-resistance: $R_{DS(ON)} = 0.318\Omega$ (typ.)

Easy to control Gate switching

Enhancement mode: $V_{th} = 2.8$ to 4.2 V

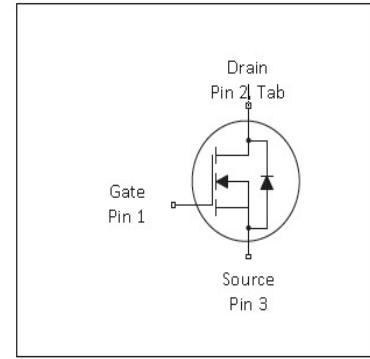


Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	700	V
$R_{DS(on),max}$	350	$m\Omega$
$Q_{g,typ}$	22	nC
$I_{D,pulse}$	33	A

3. Packaging and Internal Circuit

Part Name	Package	Marking
ASA65R350E	TO220F	ASA65R350E
ASU65R350E	TO251	ASU65R350E
ASD65R350E	TO252	ASD65R350E



1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D		-	11	A	$T_C=25^\circ\text{C}$
Pulsed drain current ²⁾	$I_{D,\text{pulse}}$	-	-	33	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	624	mJ	
MOSFET dv/dt ruggedness	dv/dt	-	-	69	V/ns	$V_{DS}=0\ldots 400\text{V}$
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Gate source voltage (dynamic)	V_{GS}	-30	-	30	V	AC ($f > 1 \text{ Hz}$)
Power dissipation(TO220F)	P_{tot}			31	W	$T_C=25^\circ\text{C}$
Power dissipation(TO251,TO252)	P_{tot}			83	W	$T_C=25^\circ\text{C}$
Storage temperature	T_{stg}	-55	-	150	°C	
Operating junction temperature	T_j	-55	-	150	°C	
Reverse diode dv/dt ³⁾	dv/dt	-	-	15	V/ns	$V_{DS}=0\ldots 400\text{V}, I_{SD} \leq 48\text{A}, T_j=25^\circ\text{C}$ see table 8

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¹⁾Limited by $T_{j,\text{max}}$. Maximum Duty Cycle D = 0.50

²⁾Pulse width t_p limited by $T_{j,\text{max}}$

³⁾Identical low side and high side switch with identical R_G

2 Thermal characteristics

Table 3 Thermal characteristics (T0220 FullPAK)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	4.0	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	80	°C/W	device on PCB, minimal footprint

Thermal characteristics (T0251 and T0252)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	device on PCB, minimal footprint

release

3 Electrical characteristics

at $T_j=25^\circ\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	655	-	-	V	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=10\text{mA}$
Gate threshold voltage	$V_{(\text{GS})\text{th}}$	2.8		4.2	V	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$
Zero gate voltage drain current	I_{DSS}	-	-	100	nA	$V_{\text{DS}}=650\text{V}, V_{\text{GS}}=0\text{V}, T_j=25^\circ\text{C}$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	-	0.318	0.35	Ω	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=5.5\text{A}, T_j=25^\circ\text{C}$
Gate resistance (Intrinsic)	R_{G}	-	11	-		$f=1\text{MHz}$, open drain

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	901	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Output capacitance	C_{oss}	-	59	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Reverse transfer capacitance	C_{rss}	-	5.3	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Turn-on delay time	$t_{\text{d}(\text{on})}$	-	7.2	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=4.8\text{A}, R_{\text{G}}=3.4\Omega$; see table 9
Rise time	t_{r}	-	20.8	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=4.8\text{A}, R_{\text{G}}=3.4\Omega$; see table 9
Turn-off delay time	$t_{\text{d}(\text{off})}$	-	29.2	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=4.8\text{A}, R_{\text{G}}=3.4\Omega$; see table 9
Fall time	t_{f}	-	19.2	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=4.8\text{A}, R_{\text{G}}=3.4\Omega$; see table 9

Table 6 Gate charge characteristics

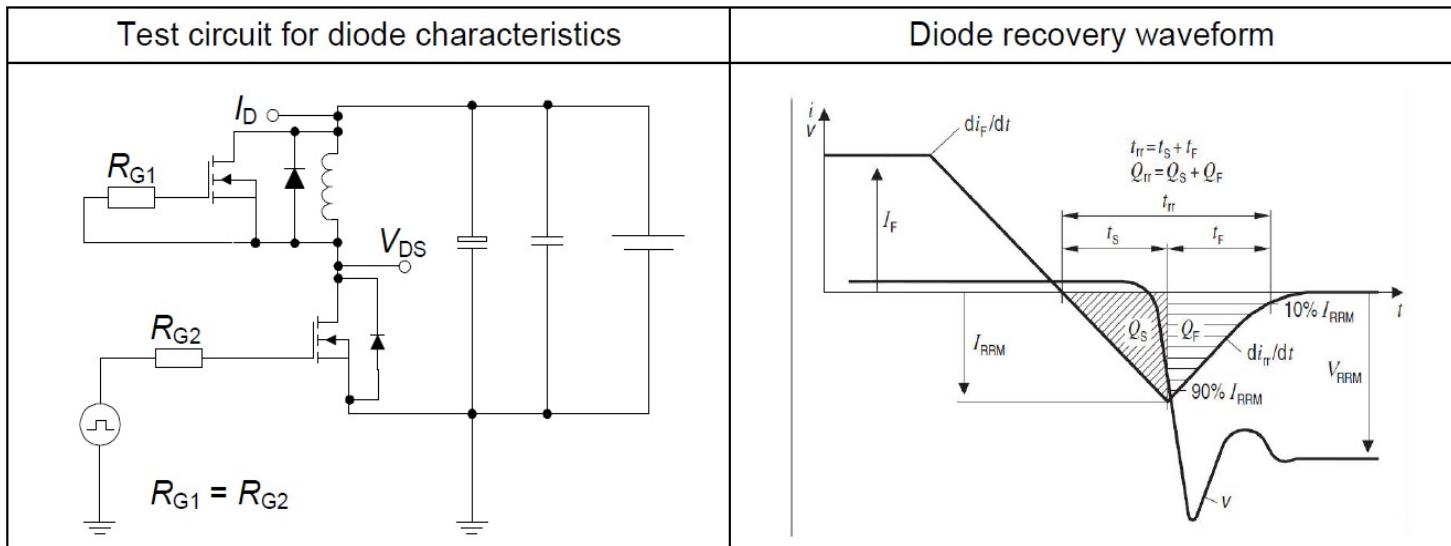
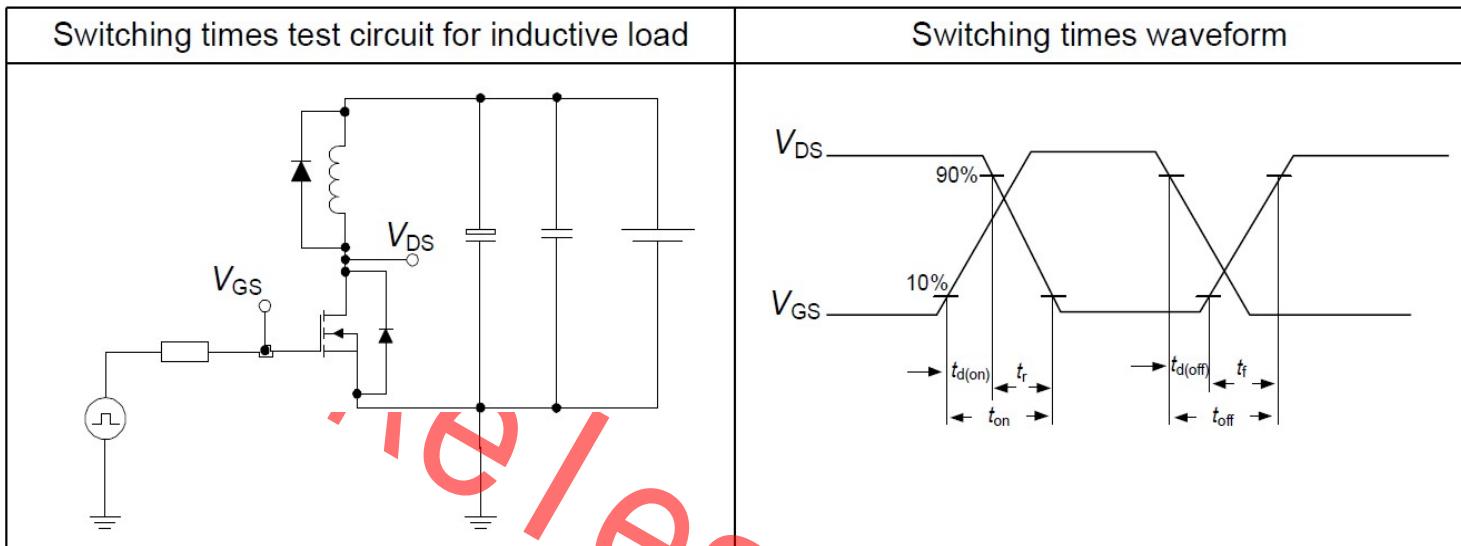
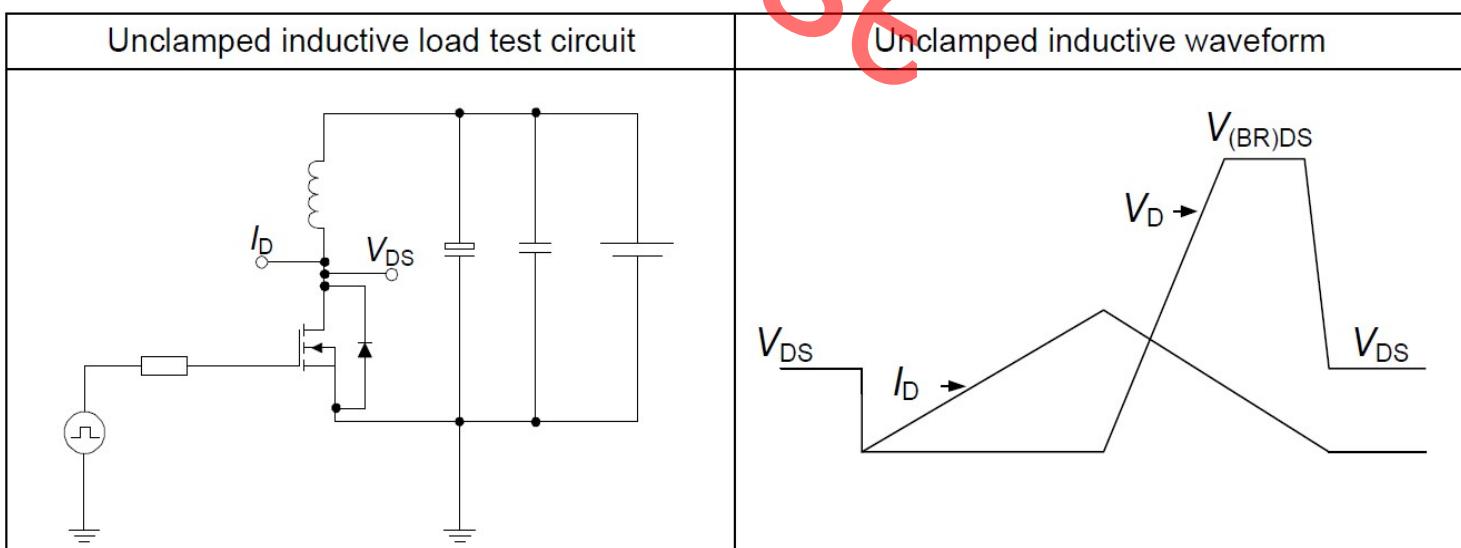
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	5.8	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=4.8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate to drain charge	Q_{gd}	-	17	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=4.8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate charge total	Q_{g}	-	22	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=4.8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate plateau voltage	V_{plateau}	-	5.3	-	V	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=4.8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$

Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.74	-	V	$V_{GS}=0V$, $I_F=1A$, $T_j=25^\circ C$
Reverse recovery time	t_{rr}	-	250	-	ns	$V_R=400V$, $I_F=4.8 A$, $di_F/dt=100A/\mu s$; see table 8
Reverse recovery charge	Q_{rr}	-	2.572	-	uC	$V_R=400V$, $I_F=4.8 A$, $di_F/dt=100A/\mu s$; see table 8
Peak reverse recovery current	I_{rrm}	-	19.6	-	A	$V_R=400V$, $I_F=4.8 A$, $di_F/dt=100A/\mu s$; see table 8

release

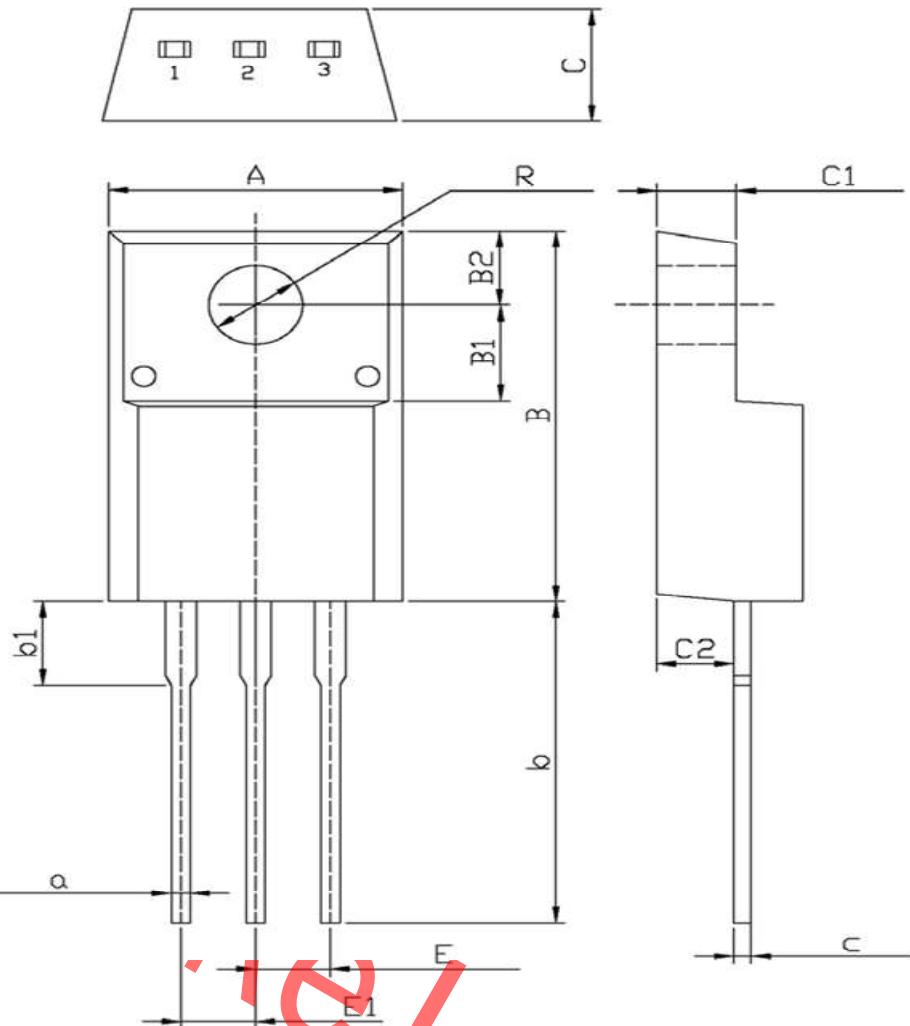
4 Test Circuits

Table 8 Diode characteristics

Table 9 Switching times

Table 10 Unclamped inductive load


5 PackageOutlines

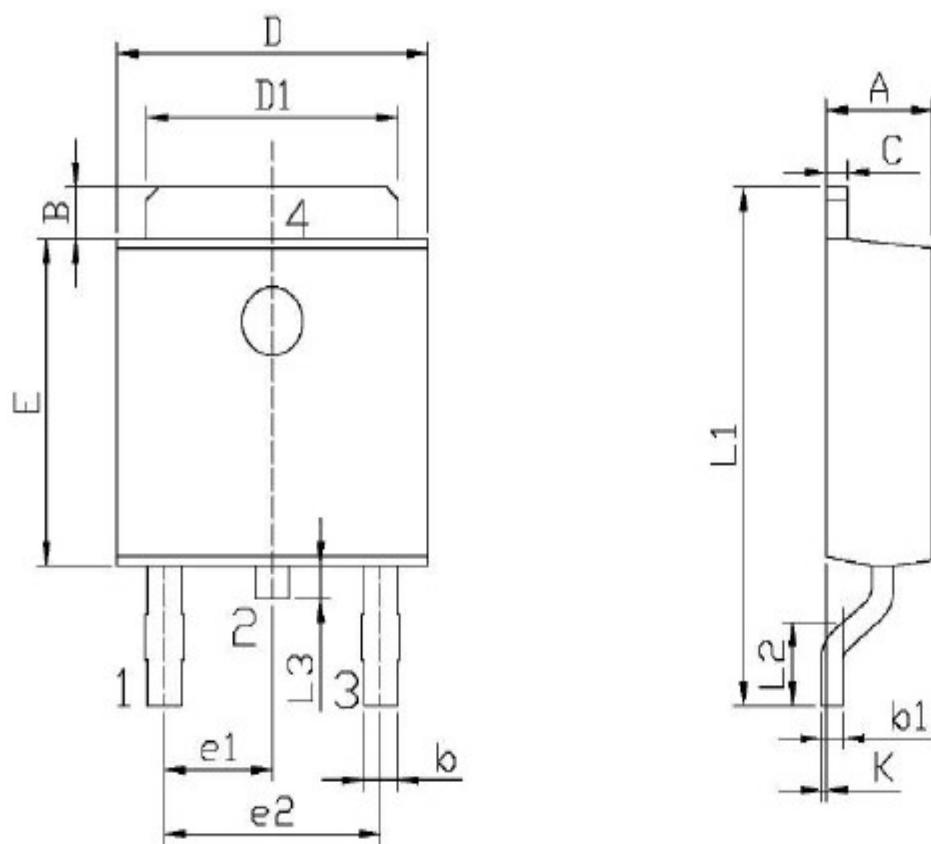
T□-220F

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	4.3	4.8	b1	2.9	3.9
A	9.7	10.3	a	0.55	0.9
B	14.7	16.1	E	2.29	2.79
B1	3.8	4	E1	2.29	2.79
B2	2.9	3.55	C1	2.5	2.9
R	3	3.4	C2	2.15	2.7
b	12.5	13.6	c	0.4	0.7

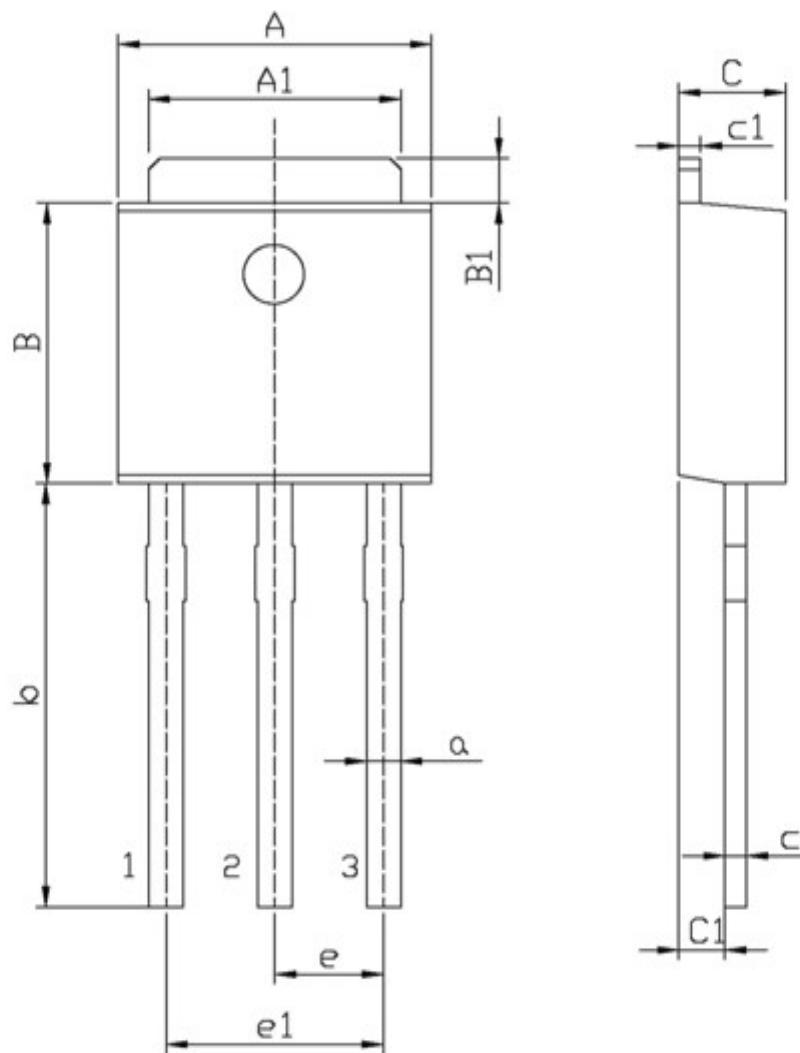
Figure1: Outline PG-T0220F



单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.70	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

Figure2: OutlinePG-T0252



单位: mm

IC
case

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	6.45	6.75	a	0.50	0.70
A1	5.10	5.50	b	9.00	9.40
B	5.95	6.25	c	0.45	0.55
B1	0.95	1.25	C1	0.45	0.55
C	2.20	2.40	e	2.24	2.34
C1	0.95	1.15	e1	4.43	4.73

Figure3: OutlinePG-T0251

Revision History**ASA65R350E**

Revision	Date	Subjects (major changes since last revision)
0.1	2019-04-12	Preliminary version
1.0	2019-11-07	Fine tune outline and add Crss test data.etc

release